
Guest editorial: 24th international conference on electronic packaging technology

This special issue is based on the 2023 24th International Conference on Electronic Packaging Technology (ICEPT), August 8–11, 2023. Well-known experts, scholars, leading enterprises, authoritative institutions and industry organizations from nearly 20 countries and regions have gathered jointly to explore the transformation and opportunities of packaging technology, industry empowerment, development and innovation in electronic packaging.

ICEPT is committed to building a bridge connecting the global packaging technology industry and better advocating and promoting an open platform for international scientific and technological community cooperation. This special issue aims to collect recent advances and developments of the ICEPT conference in China. It covers various scopes: advanced manufacturing, advanced packaging, applications of electronic technology for artificial intelligence, emerging technologies, interconnection technologies, MEMS, sensors and IoT, optoelectronics and new displays, and power electronics.

In 2023, the conference received 750 abstract submissions, 518 abstracts, 499 full-text submissions and approximately 3,300 registered authors. We collected nine papers on this issue and covered low-temperature solders, system-in-package, nano-silver sintering, silicon chip applications, Au-Al bonding, chip warpage, and stress analysis in power modules. We want to thank the 2023 24th International Conference on Electronic Packaging Technology committee members and appreciate the fruitful publication of experts in the field who participated in the submission and reviewing process for ICEPT 2023. In the future, we hope to cooperate with the ICEPT again and succeed more significantly at the 2025 26th International Conference on Electronic Packaging Technology (ICEPT).

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